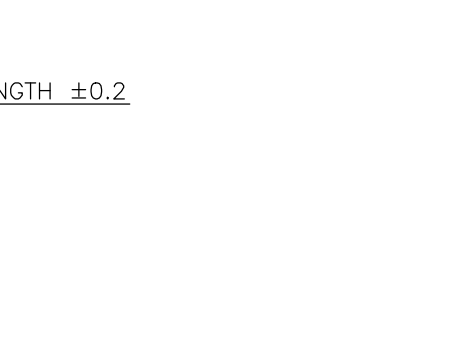
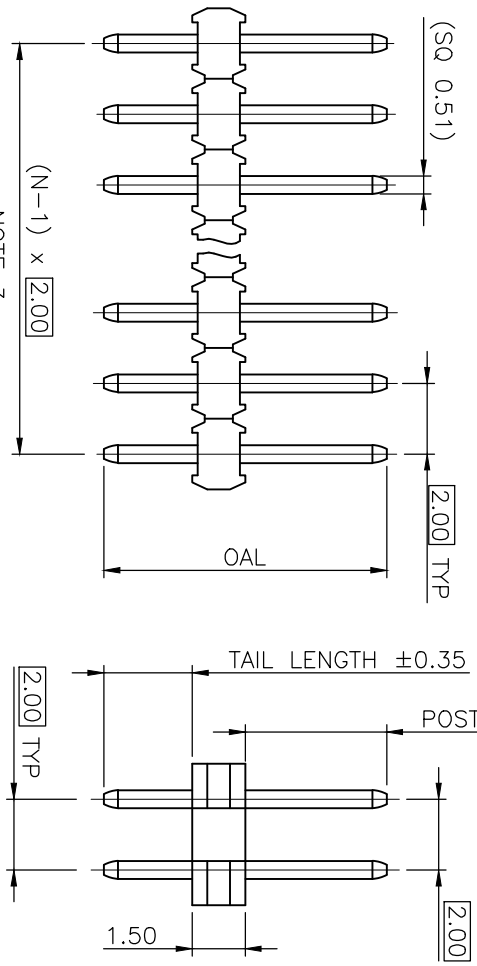
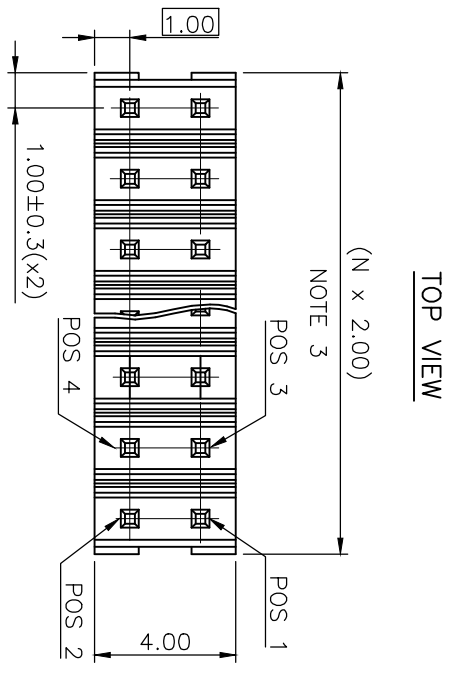


PRODUCT NUMBER
57102-XXX-XXXXXLF

PLATING _____
 S = 0.38µm GOLD/GXT ON CONTACT AREA
 2µm MIN MATTE TIN ON TAIL
 G = 0.76µm GOLD/GXT ON CONTACT AREA
 2µm MIN MATTE TIN ON TAIL
 F = GOLD FLASH ON CONTACT AREA
 2µm MIN MATTE TIN ON TAIL
 1.27µm MIN NICKEL UNDERPLATING

PIN STYLE	POST LENGTH	TAIL LENGTH	OAL
02	2.00	2.50	6.00
04	2.00	3.00	6.50
06	4.00	2.50	8.00
08	4.00	3.00	8.50
10	6.00	3.00	10.50
12	5.71	4.37	11.58



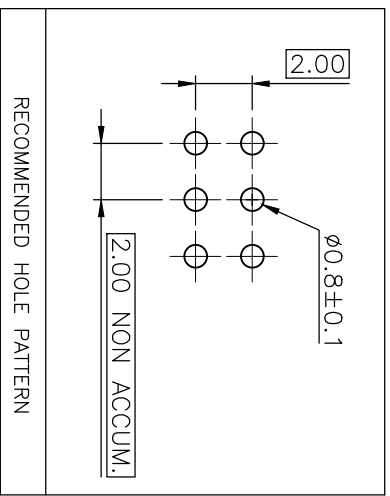
- NOTES:
- MATERIAL HOUSING: HIGH TEMP. THERMOPLASTIC
UL 94V-0, COLOR BLACK
 - MATERIAL TERMINAL: COPPER ALLOY
 - TO DETERMINE DIMENSIONS:
N = NUMBER OF POSITIONS PER ROW
 - 7N MIN. PIN RETENTION IN EITHER DIRECTION.
 - PACKAGING:
= STANDARD PACKAGING IN POLYBAGS
= PACKAGING POLYBAGS WHEN POLARIZATION FEATURE APPLICABLE
U = TUBE AVAILABLE FROM 03 TO 25 POS PER ROW
 - FOR POLARIZATION, SPECIFIED PIN
EXAMPLE : 03 = OMIT PIN POSITION 3, SEE TOP VIEW
OMIT FROM PRODUCT NUMBER IF THIS FEATURE IS NOT APPLICABLE
 - ROHS COMPATIBLE PRODUCT SPECIFICATIONS

a - PLATING:
 - "LF" MEANS THE PRODUCT IS LEAD-FREE,
 2µm MINIMUM MATTE TIN OVER 1.27µm
 MINIMUM NICKEL UNDERPLATE.

b - MANUFACTURING PROCESS COMPATIBILITY
 - THE HOUSING WILL WITHSTAND EXPOSURE TO
 260°C ±5°C SOLDER BATH TEMPERATURE FOR
 5 SECONDS IN A WAVE SOLDER APPLICATION
 WITH A 1.6mm MIN THICK CIRCUIT BOARD.
 - COMPATIBLE TO REFLOW PROCESS 260°C MAX
 FOR 30 SECONDS

c - LABELLING:
 - MEETS PACKAGING SPECS AS PER GS-14-920

d - LEGAL STATEMENT: SEE GS-47-0004



mat'l. code	surface	tolerance	projection	product family
Ltr	ecn no	dr	date	tolerances unless otherwise specified
L	F12-0062	LMU	12.05.25	angle es
M	B-19190	LMU	14.10.24	linear
N	B-19797	AMA	14.12.16	.xxx
P	B-19988	LMU	15.01.13	.xxx ±0.05
J	F08-0143	EIA	17.04.08	chp
K	F11-0026	JCO	11.05.12	qppd
	Revision		JM.C	04.11.25
	Sheet			
	Index			

product family: **MINITEK**

title: **UNSH HEADER**

2.00 mm VERTICAL TMT

dwg no: **57102**

sheet 1 of 1

size: **A3**

type: **CUSTOMER Drawing**